

07-20-1999

FORM PTO-1595

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7/19/99

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Olin Corporation
501 Merritt 7
P.O. Box 4500
Norwalk, Connecticut 06856-4500

2. Name and address of receiving party(ies):

Name: Advanced Technology Interconnect Incorporated
555 Carnegie Street, P. O. Box 952
Manteca, California 95336-0952

Additional names and addresses attached?

() Yes (X) No

3. Nature of conveyance:

(X) ASSIGNMENT () Other _____

Execution Date (1) June 21, 1999

4. Application Number(s) or Patent Number(s):

If this document is being filed together with a new application, the execution date of the Application is:

(1) (2) (3)

A. Patent Application No.(s)

B. Patent No.(s)

1. 5,477,008

[] Additional Numbers Attached

[] Additional Numbers Attached

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Gregory S. Rosenblatt
Wiggin & Dana
One Century Tower
New Haven, CT 06508-1832

6. Total number of applications and patents involved

(1)

7. Total fee (37 CFR 3.41): \$ 40.00

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8. Deposit Account No.: 23-1665

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9. Statement and signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Gregory S. Rosenblatt
Name of Person Signing
SignatureJuly 15, 1999
Date

Total number of pages comprising cover sheet (3)

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PATENT
REEL: 010086 FRAME: 0910

RECORDATION FORM COVER SHEET
(ADDED PAGE 2)

FURTHER PATENT APPLICATIONS BEING ASSIGNED:

A. Patent Application No.(s) Continued

4. 08/435,237	8. 08/755,634
5. 08/590,376	9. 08/869,376
6. 08/651,602	10. 08/891,446
7. 08/752,193	11. 08/955,191

FURTHER PATENTS BEING ASSIGNED:

B. Patent No.(s) Continued

4. 4,524,238	22. 5,098,864	40. 5,559,306
5. 4,594,770	23. 5,103,292	41. 5,578,869
6. 4,812,896	24. 5,132,773	42. 5,608,267
7. 4,827,377	25. 5,144,709	43. 5,629,835
8. 4,872,047	26. 5,155,299	44. 5,650,663
9. 4,888,449	27. 5,239,131	45. 5,688,606
10. 4,897,508	28. 5,272,800	46. 5,764,484
11. 4,928,512	29. 5,324,888	47. 5,805,427
12. 4,929,516	30. 5,360,942	
13. 4,939,316	31. 5,367,196	
14. 4,961,106	32. 5,399,805	
15. 4,967,260	33. 5,403,975	
16. 4,978,052	34. 5,455,386	
17. 5,013,871	35. 5,477,088	
18. 5,023,398	36. 5,504,372	
19. 5,043,534	37. 5,506,446	
20. 5,066,368	38. 5,534,356	
21. 5,073,521	39. 5,545,850	

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PATENT
REEL: 9781 FRAME: 0952

PATENT
REEL: 010086 FRAME: 0911

**U.S. PATENTS &
PATENT APPLICATIONS**

ASSIGNMENT

WHEREAS, OLIN CORPORATION, a corporation of Virginia with a place of business at 501 Merritt 7, P.O. Box 4500, Norwalk, Connecticut 06856-4500, is the owner of the entire right, title and interest, together with all rights of priority, in and to the following United States of America patents and applications (hereinafter referred to as "U.S. patents and applications"):

U.S. PATENTS

Inventor(s)	Title	Patent No.	Issue Date
S. H. Butt	CASING FOR AN ELECTRICAL COMPONENT HAVING IMPROVED STRENGTH AND HEAT TRANSFER CHARACTERISTICS	4,410,927	10/18/83
S. H. Butt	SEMICONDUCTOR CASING	4,461,924	07/24/84
S. H. Butt	SEMICONDUCTOR CASING	4,480,262	10/30/84
S. H. Butt	SEMICONDUCTOR PACKAGES	4,524,238	06/18/85
S. H. Butt	METHOD OF MAKING SEMICONDUCTOR CASING	4,594,770	06/17/86
E. F. Rothgery W. W. C. Hart E. F. Smith, III S. D. Phillips R. B. Sandel D. F. Gavin	METAL ELECTRONIC PACKAGE SEALED WITH THERMOPLASTIC HAVING A GRAFTED METAL DEACTIVATOR AND ANTIOXIDANT	4,812,896	03/14/89
S. H. Butt	MULTI-LAYER CIRCUITRY	4,827,377	05/02/89
J. C. Fister S. C. Cherukuri D. Mahulikar B. E. O'Donnely	SEMICONDUCTOR DIE ATTACH SYSTEM	4,872,047	10/03/89
J. Crane B. C. Johnson D. Mahulikar S. H. Butt	SEMICONDUCTOR PACKAGE	4,888,449	12/19/89
D. Mahulikar S. H. Butt J. Crane A. M. Pasqualoni E. F. Smith, III	METAL ELECTRONIC PACKAGE	4,897,508	01/30/90

**PATENT
REEL: 9781 FRAME: 0953**

**PATENT
REEL: 010086 FRAME: 0912**

Inventor(s)	Title	Patent No.	Issue Date
J. F. Rooney H. P. Cheskis	DIE SET FOR THE FORMATION OF CAVITIES FOR METAL PACKAGES TO HOUSE ELECTRONIC DEVICES	4,928,512	05/29/90
M. J. Pryor J. C. Fister	SEMICONDUCTOR GRADED DIE ATTACH SYSTEM	4,929,516	05/29/90
D. Mahulikar J. M. Popplewell	ALUMINUM ALLOY SEMICONDUCTOR PACKAGES	4,939,316	07/03/90
S. H. Butt	METAL PACKAGES HAVING IMPROVED THERMAL DISSIPATION	4,961,106	10/02/90
S. H. Butt	HERMETIC MICROMINIATURE PACKAGES	4,967,260	10/30/90
J. C. Fister S. C. Cherukuri D. Mahulikar B. E. O'Donnelly	SEMICONDUCTOR DIE ATTACH SYSTEM	4,978,052	12/18/90
D. Mahulikar S. H. Butt J. Crane A. M. Pasqualoni E. F. Smith, III	KIT FOR THE ASSEMBLY OF A METAL ELECTRONIC PACKAGE	5,013,871	05/07/91
D. Mahulikar J. M. Popplewell	ALUMINUM ALLOY SEMICONDUCTOR PACKAGES	5,023,398	06/11/91
D. Mahulikar J. S. Braden S. P. Noe	METAL ELECTRONIC PACKAGE HAVING IMPROVED RESISTANCE TO ELECTROMAGNETIC INTERFERENCE	5,043,534	08/27/91
A. M. Pasqualoni D. Mahulikar S. K. Jalota A. J. Brock	PROCESS FOR PRODUCING BLACK INTEGRALLY COLORED ANODIZED ALUMINUM COMPONENTS	5,066,368	11/19/91
J. S. Braden	METHOD FOR HOUSING A TAPE BONDED ELECTRONIC DEVICE AND THE PACKAGE EMPLOYED	5,073,521	12/17/91
D. Mahulikar	PROCESS FOR MANUFACTURING A METAL PIN GRID ARRAY PACKAGE	5,098,864	03/24/92
D. Mahulikar	METAL PIN GRID ARRAY PACKAGE	5,103,292	04/07/92
J. S. Braden M. Penry	CARRIER RING HAVING FIRST AND SECOND RING MEANS WITH BONDED SURFACES	5,132,773	07/21/92
J. F. Rooney	FORMATION OF SHAPES IN A METAL WORKPIECE	5,144,709	09/08/92
D. Mahulikar J. M. Popplewell	ALUMINUM ALLOY SEMICONDUCTOR PACKAGES	5,155,299	10/13/92

Inventor(s)	Title	Patent No.	Issue Date
P. R. Hoffman L. E. Strauman D. Liang S. S. Pareno G. J. Ramirez	ELECTRONIC PACKAGE HAVING CONTROLLED EPOXY FLOW	5,239,131	08/24/93
J. F. Rooney W. G. Park	METHOD AND APPARATUS FOR FORMING AND POSITIONING A PREFORM ON A WORKPIECE	5,272,800	12/28/93
D. E. Tyler D. Mahulikar A. M. Pasqualoni J. S. Braden P. R. Hoffman	METAL ELECTRONIC PACKAGE WITH REDUCED SEAL WIDTH	5,324,888	06/28/94
P. R. Hoffman D. Liang	MULTI-CHIP ELECTRONIC PACKAGE MODULE UTILIZING AN ADHESIVE	5,360,942	11/01/94
D. Mahulikar J. S. Braden S. F. Chen	MOLDED PLASTIC SEMICONDUCTOR PACKAGE INCLUDING AN ALUMINUM ALLOY HEAT SPREADER	5,367,196	11/22/94
D. E. Tyler D. Mahulikar A. M. Pasqualoni J. S. Braden P. R. Hoffman	METAL ELECTRONIC PACKAGE WITH REDUCED SEAL WIDTH	5,399,805	03/21/95
A. M. Pasqualoni D. Mahulikar S. K. Jalota A. J. Brock	PROCESS FOR PRODUCING BLACK INTEGRALLY COLORED ANODIZED ALUMINUM COMPONENTS	5,403,975	04/04/95
G. A. Brathwaite R. Ruble G. J. Ramirez M. A. Holmes P. R. Hoffman D. Liang	CHAMFERED MQUAD PIECE PART FOR CONTROLLING SEAL EPOXY	5,455,386	10/03/95
A. M. Pasqualoni D. Mahulikar S. Jewell P. R. Hoffman G. A. Brathwaite R. McNabb G. J. Ramirez	POLYMER PLUG FOR ELECTRONIC PACKAGE	5,477,088	12/19/95
J. S. Braden J. Crane D. Mahulikar	ADHESIVELY SEALED METAL ELECTRONIC PACKAGE INCORPORATING A MULTI-CHIP MODULE	5,504,372	04/02/96

Inventor(s)	Title	Patent No.	Issue Date
P. R. Hoffman, G. A. Brathwaite D. D. Bui D. Mahulikar	ELECTRONIC PACKAGE HAVING IMPROVED WIRE BONDING CAPABILITY	5,506,446	04/09/96
D. Mahulikar E. Sagiv A. Parthasarathi S. K. Jalota A. J. Brock M. A. Holmes J. M. Schlater G. J. Ramirez D. Liang	ANODIZED ALUMINUM SUBSTRATES HAVING INCREASED BREAKDOWN VOLTAGE	5,534,356	07/09/96
D. Mahulikar P. R. Hoffman	GUARD RING FOR INTEGRATED CIRCUIT PACKAGE	5,545,850	08/13/96
D. Mahulikar	ELECTRONIC PACKAGE WITH IMPROVED ELECTRICAL PERFORMANCE	5,559,306	09/24/96
P. R. Hoffman D. Mahulikar G. A. Brathwaite D. Solomon A. Parthasarathi	COMPONENTS FOR HOUSING AN INTEGRATED CIRCUIT DEVICE	5,578,869	11/26/96
D. Mahulikar D. E. Tyler J. S. Braden J. M. Popplewell	MOLDED PLASTIC SEMICONDUCTOR PACKAGE INCLUDING AN ALUMINUM ALLOY HEAT SPREADER	5,608,267	03/04/97
D. Mahulikar P. R. Hoffman J. S. Braden	METAL BALL GRID ARRAY PACKAGE WITH IMPROVED THERMAL CONDUCTIVITY	5,629,835	05/13/97
A. Parthasarathi	ELECTRONIC PACKAGE WITH IMPROVED THERMAL PROPERTIES	5,650,663	07/22/97
D. Mahulikar E. Sagiv A. Parthasarathi S. K. Jalota A. J. Brock M. A. Holmes J. M. Schlater G. J. Ramirez D. Liang	ANODIZED ALUMINUM SUBSTRATE HAVING INCREASED BREAKDOWN VOLTAGE	5,688,606	11/18/97
P. R. Hoffman M. K. Leibhard	GROUND RING FOR A METAL ELECTRONIC PACKAGE	5,764,484	06/09/98
P. R. Hoffman	BALL GRID ARRAY ELECTRONIC PACKAGE STANDOFF DESIGN	5,805,427	09/08/98

U.S. PATENT APPLICATIONS

Inventor(s)	Title	Serial No.	Filing Date
D. Mahulikar J. Crane A. A. Khan	THERMAL PERFORMANCE PACKAGE FOR INTEGRATED CIRCUIT CHIP	07/984,147	11/24/92
D. Mahulikar P. R. Hoffman J. S. Braden	BALL GRID ARRAY ELECTRONIC PACKAGE	08/033,596	03/19/93
A. Parthasarathi D. Mahulikar	SEMICONDUCTOR PACKAGE WITH MOLDED PLASTIC BODY	08/249,104	05/25/94
J. S. Braden J. Crane D. Mahulikar	EDGE CONNECTABLE METAL PACKAGE	08/435,237	05/05/95
D. Liang G. A. Brathwaite P. R. Hoffman G. J. Ramirez L. E. Strauman D. Mahulikar A. M. Pasqualoni	ELECTRONIC PACKAGE SEALED WITH A DISPENSABLE ADHESIVE	08/590,376	01/25/96
D. Mahulikar A. Parthasarathi P. R. Hoffman J. S. Braden	METAL ELECTRONIC PACKAGE WITH PERIPHERALLY ATTACHED LEADS	08/651,602	05/22/96
G. A. Brathwaite S. A. Tostado P. R. Hoffman	SEMICONDUCTOR PACKAGE HAVING A GROUND RING AND A METAL SUBSTRATE	08/752,193	11/18/96
D. Mahulikar P. R. Hoffman J. S. Braden	INTEGRALLY BUMPED ELECTRONIC PACKAGE COMPONENTS	08/755,634	11/25/96
P. R. Hoffman	SOLDER JOINT RELIABILITY	08/869,376	06/05/97
P. W. Robinson D. Mahulikar P. R. Hoffman	METAL BALL GRID ARRAY DESIGNS FOR IMPROVED SOLDER JOINT	08/891,446	07/10/97
A. Parthasarathi S. Jalota J. Schlater L. Strauman J. S. Braden	ALUMINUM ALLOYS FOR ELECTRICAL COMPONENTS	08/955,191	10/21/97

WHEREAS, ADVANCED TECHNOLOGY INTERCONNECT INCORPORATED, doing business as ADVANCED INTERCONNECT TECHNOLOGIES, a corporation of California with a place of

business at 555 Carnegie Street, P. O. Box 952, Manteca, California 95336-0952 is desirous of acquiring the following assets (hereinafter referred to as the "Patent Assets"):

- a) said U.S. patents and patent applications and the inventions thereof, including any patents or patent applications comprising: divisions, continuations, continuations-in-part and reissues of said U.S. patents and patent applications; and
- b) all foreign counterpart patents or patent applications derived from said U.S. patents and patent applications or any such divisions, continuations, continuations-in-part and reissues of said U.S. patents and patent applications.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, said OLIN CORPORATION does hereby sell, assign and transfer to said ADVANCED TECHNOLOGY INTERCONNECT INCORPORATED, doing business as ADVANCED INTERCONNECT TECHNOLOGIES all of its right, title and interest, together with all rights of priority, in and to said Patent Assets.

OLIN CORPORATION further agrees that when requested it will without charge to said ADVANCED TECHNOLOGY INTERCONNECT INCORPORATED, doing business as ADVANCED INTERCONNECT TECHNOLOGIES, but at its expense, cause all papers and rightful oaths to be signed, and do all acts which may be reasonably necessary, for securing and maintaining patents and patent applications for said inventions in any and all countries and for vesting title thereto in ADVANCED TECHNOLOGY INTERCONNECT INCORPORATED, doing business as ADVANCED INTERCONNECT TECHNOLOGIES, its successors, assigns, legal representatives or nominees.

OLIN CORPORATION DOES NOT REPRESENT OR WARRANT THAT THE PATENT ASSETS
ASSIGNED HEREBY ARE VALID OR ENFORCEABLE, OR THAT THE INVENTIONS CLAIMED
THEREIN ARE FIT FOR ANY PARTICULAR USE OR PURPOSE.

OLIN CORPORATION

By Johnnie M. Jackson, Jr.
Johnnie M. Jackson, Jr.

Title Vice President, General Counsel and Secretary

STATE OF CONNECTICUT)
COUNTY OF Fairfield) SS.

On this 19th day of February, 1999, before me a Notary Public in and for
said County and State, personally appeared Johnnie M. Jackson, Jr. who being duly sworn, deposes and
says that he is Vice President, General Counsel and Secretary of OLIN CORPORATION the corporation
described in the above ASSIGNMENT and that he executed the above ASSIGNMENT as a free act on
behalf of OLIN CORPORATION.

Brenda M. Pantalone
Notary Public

SEAL:

My Commission Exp. Nov. 30, 2002

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PATENT
REEL: 9781 FRAME: 0959

RECORDED: 07/19/1999

PATENT
REEL: 010086 FRAME: 0918